Muneeb Zia

List of Publications by Year
in descending order

		1684188	1720034
10 papers	83 citations	5 h-index	7 g-index
11 all docs	11 docs citations	11 times ranked	76 citing authors

#	Article	IF	Citations
1	Flexible Multielectrode Arrays With 2-D and 3-D Contacts for $In\sim Vivo$ Electromyography Recording. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 197-202.	2.5	11
2	Fabrication and Characterization of 3D Multi-Electrode Array on Flexible Substrate for In Vivo EMG Recording from Expiratory Muscle of Songbird. , 2018, 2018, 29.4.1-29.4.4.		7
3	Post-CMOS Fabrication Technology Enabling Simultaneous Fabrication of 3-D Solenoidal Micro-Inductors and Flexible I/Os. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 2039-2044.	2.5	3
4	Heterogeneous Interconnect Stitching Technology With Compressible MicroInterconnects for Dense Multi-Die Integration. IEEE Electron Device Letters, 2017, 38, 255-257.	3.9	15
5	Design, Fabrication, and Characterization of Dense Compressible Microinterconnects. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1003-1010.	2.5	14
6	Dense and Highly Elastic Compressible MicroInterconnects (CMIs) for Electronic Microsystems. , 2017, , .		3
7	3-D Integrated Electronic Microplate Platform for Low-Cost Repeatable Biosensing Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1827-1833.	2.5	5
8	Thermal Isolation Using Air Gap and Mechanically Flexible Interconnects for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 31-39.	2.5	13
9	A Memory-Based Logic Block With Optimized-for-Read SRAM for Energy-Efficient Reconfigurable Computing Fabric. IEEE Transactions on Circuits and Systems II: Express Briefs, 2015, 62, 593-597.	3.0	8
10	Interposer-to-interposer electrical and silicon photonic interconnection platform using silicon bridge. , 2014, , .		4